



SYMBOL	DIMENSIONS IN MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	—	—	1.20	
A ₁	0.05	—	0.15	
A ₂	0.95	1.00	1.05	
b	0.17	0.22	0.27	
b ₁	0.17	0.20	0.23	
c	0.10	—	0.21	
c ₁	0.10	—	0.16	
D	19.80	—	20.20	2
D ₁	18.40	—	18.50	3
E	11.90	—	12.10	3
e	0.50 BSC			
L	0.50	0.60	0.70	
N	48			
α	0°	3°	5°	

NOTES:

- DIMENSIONS & TOLERANCES PER ASME Y14.5M. — 1994.
- DATUM [A-B] AND [D] TO BE DETERMINED WHERE CENTERLINE BETWEEN LEADS EXIST PLASTIC BODY AT DATUM PLANE [H].
- "D₁" & "E" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, AND ARE MEASURED AT THE PARTING LINE, MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15mm ON "E" AND 0.25 ON "D₁" PER SIDE.
- THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND AN ADJACENT LEAD TO BE 0.07mm. SEE SECTION "C-C".
- LEAD FINISH: VO48 — 85/15 (Sn/Pb)
VOG48 — 100% Matte Sn or Ni/Pd/Au
- CONTROLLING DIMENSION: MILLIMETERS.
- THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION MO-142 VARIATION DD.

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/23/05	1.2.1	No previous revision history.
10/11/10	1.3	Added "or Ni/Pd/Au" to Note 5.

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.